



FOR IMMEDIATE RELEASE

Aehr Test Systems

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Reminder: Aehr Test Systems to Participate in CEO Investor Summit in San Francisco on July 9, 2014

Investor Presentation to be Posted on Company Website

Fremont, CA (July 8, 2014) – Aehr Test Systems (NASDAQ: AEHR), a worldwide supplier of semiconductor test and burn-in equipment, today reminded investors that Gayn Erickson, President and CEO, will participate in the Sixth Annual CEO Investor Summit 2014 on Wednesday, July 9, 2014 in San Francisco, California. Mr. Erickson’s presentation will be made available on the day of the event in the Investor Relations section of Aehr Test’s website at www.aehr.com.

About The Sixth Annual CEO Summit

The CEO Summit is an accredited investor and publishing research analyst event that is held concurrently (though not affiliated) with SEMICON West and Intersolar 2014 in San Francisco. The event is hosted by executive management from participating companies and will feature a “round-robin” format consisting of small group meetings, each 30 minutes in duration. The CEO Investor Summit is by invitation only and is open to accredited investors and publishing research analysts.

About Aehr Test Systems

Headquartered in Fremont, California, Aehr Test Systems is a worldwide provider of test systems for burning-in and testing logic and memory integrated circuits and has an installed base of more than 2,500 systems worldwide. Increased quality and reliability needs of the Automotive and Mobility integrated circuit markets are driving additional test requirements, capacity needs and opportunities for Aehr Test products in package and wafer level test. Aehr Test has developed and introduced several innovative products, including the ABTS™ and FOX™ families of test and burn-in systems and the DiePak® carrier. The ABTS system is used in production and qualification testing of packaged parts for both low-power and high-power logic as well as all common types of memory devices. The FOX system is a full wafer contact test and burn-in system used for burn-in and functional test of complex devices, such as leading-edge memories, digital signal processors, microprocessors, microcontrollers and systems-on-a-chip. The DiePak carrier is a reusable, temporary package that enables IC manufacturers to perform cost-effective final test and burn-in of bare die. For more information, please visit the Company’s website at www.aehr.com.

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